

The present invention is directed to a semi-conductor handling equipment cleaning method and apparatus configured for use with wafer carriers. The cleaning apparatus comprises a base portion having a first aperture and a second aperture. The base is configured to support the wafer carrier in sealing contact about the first aperture. A first fluidic circuit is provided for introducing a first cleaning fluid to the inner surface of the carrier. A second fluidic circuit is provided for introducing a second cleaning fluid to the outer surface of the carrier. The carrier forms a barrier with the base so that the cleaning media is isolated so as to substantially prevent the second fluid used to clean the exterior from communicating with the first fluid used to clean the interior of the carrier.

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